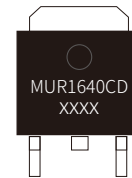
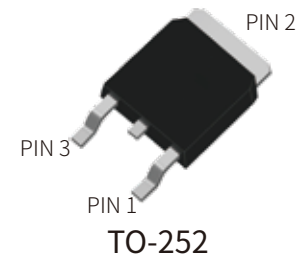
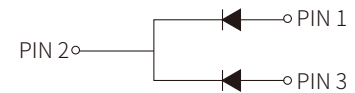


FEATURES

- | Adopt Fred Chip
- | Low Forward Voltage Drop
- | Fast Reverse Recovery Time
- | High Frequency Operation
- | High Purity, High Temperature Epoxy Encapsulation For Enhanced Mechanical Strength And Moisture Resistance
- | Guard Ring For Enhanced Ruggedness And Long Term Reliability



Marking



Schematic Symbol

APPLICATIONS

- | Typical Applications Are In Switching Power Supplies, Converters, Freewheeling Diodes, And Reverse Battery Protection

APPROVALS

| | |
|-------------|------------------------------------|
| RoHS | Compliance with 2011/65/EU |
| HF | Compliance with IEC61249-2-21:2003 |

MAXIMUM RATINGS (T_A=25°C)

| Parameter | Symbol | Value | Unit |
|--|-------------------|------------|------------------|
| Repetitive Peak Reverse Voltage | V _{RRM} | 400 | V |
| Average Rectified Output Current @60Hz sine wave, R-load, T _c (FIG.1) | I _o | 16 | A |
| Surge(Non-repetitive)Forward Current @60Hz half sine-wave, 1 cycle, T _j =25°C | I _{FSM} | 100 | A |
| Current Squared Time @1ms≤t≤8.3ms T _j =25°C | I ² t | 41 | A ² s |
| Typical Junction capacitance @4V,1MHz | C _J | 40 | pF |
| Thermal Resistance Between Junction and Case | R _{θJ-C} | 5 | °C/W |
| Thermal Resistance Between Junction and Air | R _{θJ-A} | 50 | °C/W |
| Junction Temperature | T _J | -55 to 175 | °C |
| Storage Temperature | T _{STG} | -55 to 175 | °C |

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

| Parameter | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
|---|------------------|---|------|-------|------|------|
| Instantaneous Forward Voltage Drop Per Diode | V _{FM} | I _{FM} = 8.0A @ T _J = 25°C | | 1.15 | 1.30 | V |
| | | I _{FM} = 8.0A @ T _J = 150°C | | 0.9 | 1.0 | |
| DC Reverse Current at Rated DC Blocking Voltage Per Diode | I _R | V _{RM} = V _{RRM} , T _J = 25°C | | | 5 | μA |
| | | V _{RM} = V _{RRM} , T _J = 150°C | | 30 | 100 | |
| Reverse Recovery Time | T _{rr} | I _F = 0.5A, I _{RM} = 1A I _{RR} = 0.25A, T _J = 25°C | | 25 | 35 | ns |
| | | I _F = 8A, di/dt = -200A/μs V _{RM} = 200V, T _J = 25°C | | 33.3 | | |
| | | I _F = 8A, di/dt = -200A/μs V _{RM} = 200V, T _J = 125°C | | 54.5 | | |
| Peak Recovery Current | I _{RRM} | I _F = 8A, di/dt = -200A/μs V _{RM} = 200V, T _J = 25°C | | 3.39 | | A |
| | | I _F = 8A, di/dt = -200A/μs V _{RM} = 200V, T _J = 125°C | | 6.17 | | |
| Reverse Recovery Charge | Q _{rr} | I _F = 8A, di/dt = -200A/μs V _{RM} = 200V, T _J = 25°C | | 56.17 | | nC |
| | | I _F = 8A, di/dt = -200A/μs V _{RM} = 200V, T _J = 125°C | | 180 | | |

CHARACTERISTIC CURVES

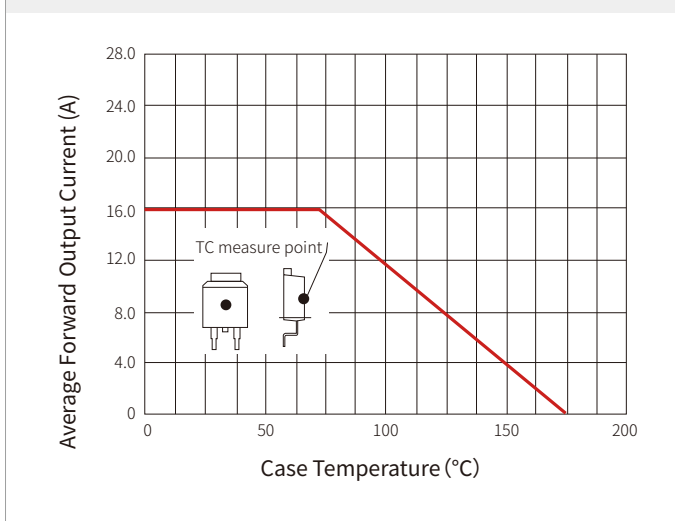
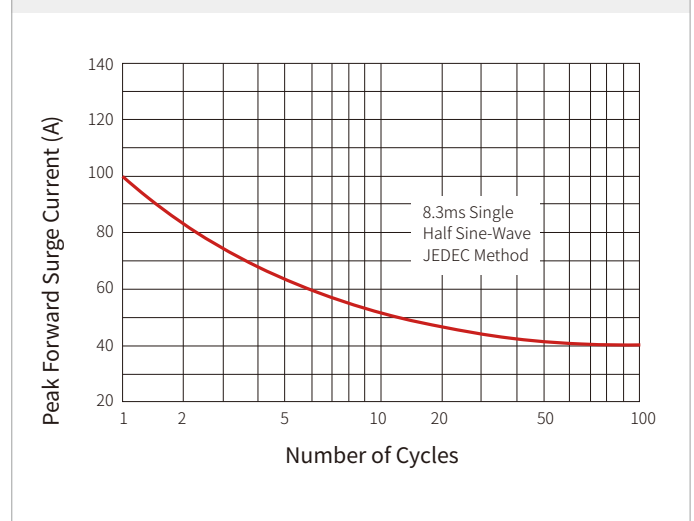
FIG1: I_o - T_c Curve

FIG2: Surge Forward Current Capability


FIG3: Forward Voltage

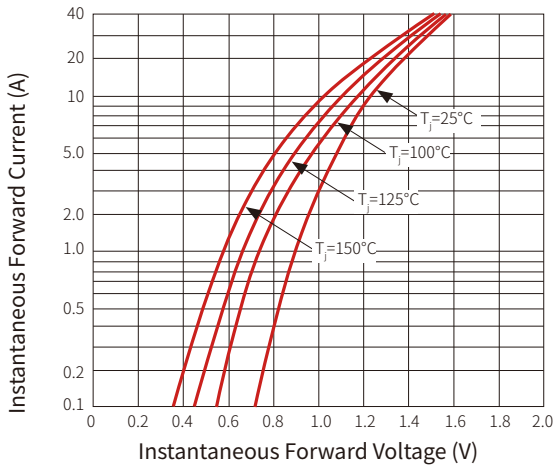


FIG.4: Instantaneous Reverse Characteristics

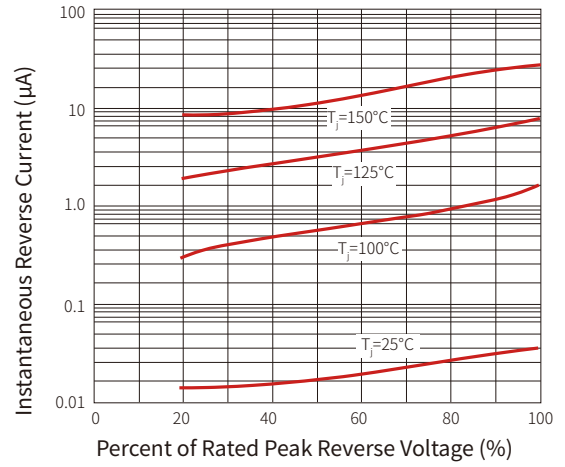
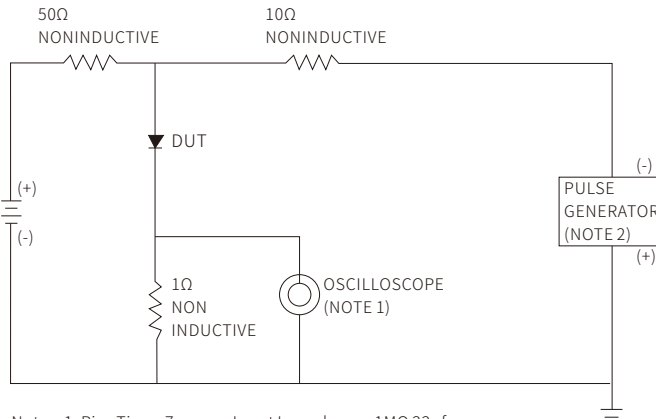
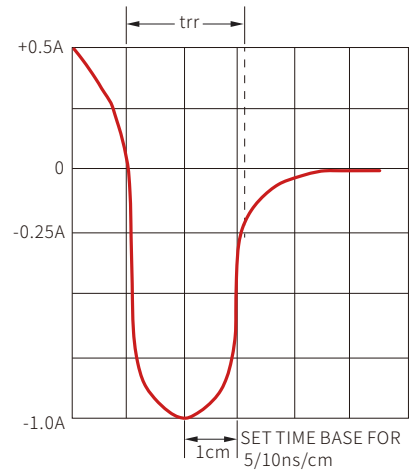


FIG.5: Diagram of circuit and Testing wave form of reverse recovery time

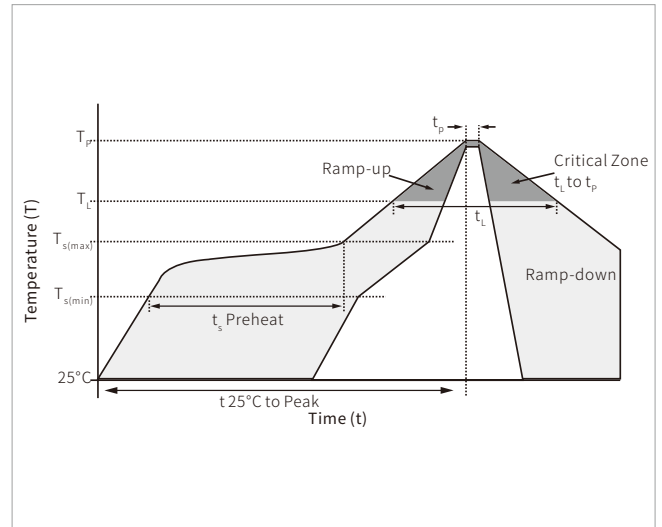


Notes: 1. Rise Time=7ns max. Input Impedance=1MΩ 22pf
2. Rise Time=10ns max. Source Impedance=50Ω

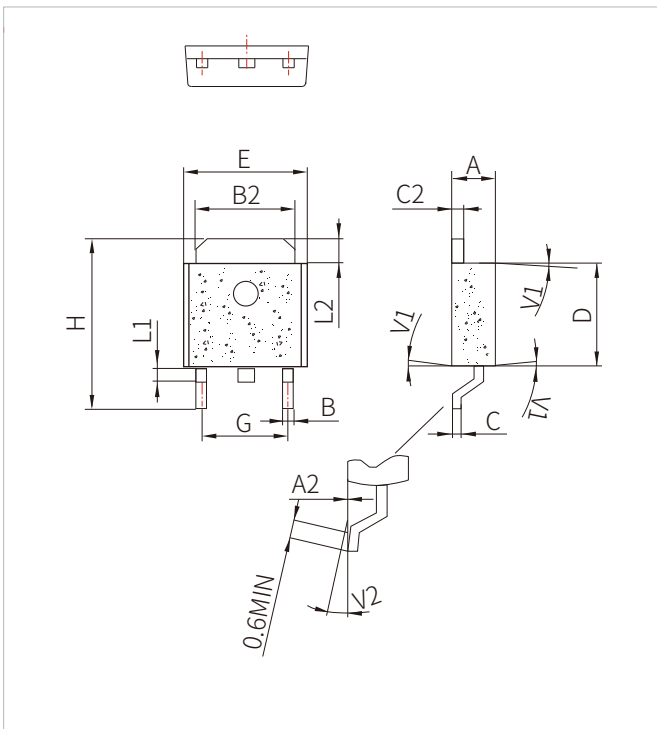


SOLDERING PARAMETERS

| Reflow Condition | | Lead-free assembly |
|--|----------------------------------|--------------------|
| Pre Heat | Temperature Max ($T_{s(min)}$) | 150°C |
| | Temperature Max ($T_{s(max)}$) | 200°C |
| | Time (min to max) (t_s) | 60 – 180 secs |
| Average ramp up rate (Liquidus Temp (T_L) to peak) | | 3°C/second max |
| $T_{s(max)}$ to T_L - Ramp-up Rate | | 3°C/second max |
| Reflow | Temperature (T_L) (Liquidus) | 217°C |
| | Time (min to max) (t_l) | 60 – 150 seconds |
| Peak Temperature (T_p) | | 260°C |
| Time within 5°C of actual peak Temperature (t_p) | | 20 – 40 seconds |
| Ramp-down Rate | | 6°C/second max |
| Time 25°C to peak Temperature (T_p) | | 8 minutes max. |
| Do not exceed | | 260°C |



TO-252 PACKAGE MECHANICAL DATA



| Ref. | Dimensions | | | | | |
|------|-------------|------|------|--------|-------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 2.10 | | 2.50 | 0.083 | | 0.098 |
| A2 | 0.03 | | 0.23 | 0.001 | | 0.009 |
| B | 0.55 | | 0.65 | 0.022 | | 0.026 |
| B2 | 5.10 | | 5.40 | 0.200 | | 0.213 |
| C | 0.45 | | 0.62 | 0.018 | | 0.024 |
| C2 | 0.48 | | 0.62 | 0.019 | | 0.024 |
| D | 6.00 | | 6.20 | 0.236 | | 0.244 |
| E | 6.40 | | 6.80 | 0.252 | | 0.268 |
| G | 4.40 | | 4.70 | 0.173 | 0.1 | 0.185 |
| H | 9.35 | | 10.7 | 0.368 | | 0.421 |
| L1 | 1.30 | | 1.70 | 0.051 | 0.143 | 0.067 |
| L2 | 1.37 | | 1.50 | 0.054 | | 0.059 |
| V1 | | 4° | | | 0.130 | |
| V2 | 0° | | 8° | 0° | | 8° |

ORDERING INFORMATION

| Part Number | Component Package | QTY/Reel | Reel Size |
|-------------|-------------------|----------|-----------|
| MUR1640CD | TO-252 | 2500PCS | 13" |

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